



US 20220377913A1

(19) **United States**

(12) **Patent Application Publication**
CHEN et al.

(10) **Pub. No.: US 2022/0377913 A1**

(43) **Pub. Date: Nov. 24, 2022**

(54) **METHOD FOR MANUFACTURING CIRCUIT BOARD WITH HEAT DISSIPATION FUNCTION**

Publication Classification

(51) **Int. Cl.**
H05K 3/46 (2006.01)
H05K 3/38 (2006.01)
(52) **U.S. Cl.**
CPC **H05K 3/4676** (2013.01); **H05K 3/388** (2013.01); **B82Y 40/00** (2013.01)

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(21) Appl. No.: **17/354,478**

(22) Filed: **Jun. 22, 2021**

(30) **Foreign Application Priority Data**

May 24, 2021 (CN) 202110563540.0

(57) **ABSTRACT**
A method for manufacturing a circuit board, includes: stacking a first peelable film on a second peelable film, and disposing fluffy carbon nanotubes between the first peelable film and the second peelable film, thereby obtaining a carbon nanotube layer; pressing the first peelable film, the carbon nanotube layer, and the second peelable film to compact the fluffy carbon nanotubes, thereby obtaining a thermal conductive layer; removing the first peelable film, and disposing a first adhesive layer, a first dielectric layer, and a first circuit layer on a side of the thermal conductive layer away from the second peelable film; removing the second peelable film, and disposing a second adhesive layer, a second dielectric layer, and a second circuit layer on a side of the thermal conductive layer away from the first adhesive layer; mounting an electronic component on the first circuit layer.

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